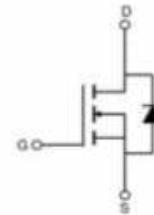


Feature

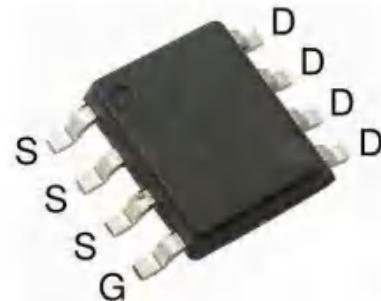
- 30V,20A
- $R_{DS(on)} < 6m\Omega @ V_{GS}=10V$
- $R_{DS(on)} < 9m\Omega @ V_{GS}=4.5V$
- Advanced Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(on)}$ and Low Gate Charge



Schematic Diagram

Application

- PWM applications
- Load Switch
- Power management



SOP-8

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity (PCS) |
|----------------|---------|----------------|-----------|------------|----------------|
| 3004S | AP3004S | SOP-8 | 13 inch | - | 4000 |

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|--|-----------------|----------|------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current ($T_a = 25^\circ C$) | I_D | 20 | A |
| Continuous Drain Current ($T_a = 100^\circ C$) | I_D | 14 | A |
| Pulsed Drain Current ⁽¹⁾ | I_{DM} | 52 | A |
| Singel Pulsed Avalanche Energy ⁽²⁾ | E_{AS} | 64.8 | mJ |
| Power Dissipation | P_D | 3 | W |
| Thermal Resistance from Junction to Ambient ⁽⁴⁾ | $R_{\theta JA}$ | 42 | °C/W |
| Junction Temperature | T_J | 150 | °C |
| Storage Temperature | T_{STG} | -55~+150 | °C |

MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Test Condition | Min | Type | Max | Unit |
|---|---------------|---|-----|------|-----------|-----------|
| Static Characteristics | | | | | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 30 | - | - | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS} = 30V, V_{GS} = 0V$ | - | - | 1 | μA |
| Gate-body leakage current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | - | - | ± 100 | nA |
| Gate threshold voltage ⁽³⁾ | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1 | 1.5 | 2.5 | V |
| Drain-source on-resistance ⁽³⁾ | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | - | 5.0 | 6.0 | $m\Omega$ |
| | | $V_{GS} = 4.5V, I_D = 10A$ | - | 7.0 | 9.0 | |
| Dynamic characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$ | - | 1614 | - | pF |
| Output Capacitance | C_{oss} | | - | 245 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 215 | - | |
| Switching characteristics | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD} = 15V, I_D = 20A,$ $V_{GS} = 10V, R_G = 3\Omega$ | - | 7.5 | - | ns |
| Turn-on rise time | t_r | | - | 14.5 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 35.2 | - | |
| Turn-off fall time | t_f | | - | 9.6 | - | |
| Total Gate Charge | Q_g | $V_{DS} = 15V, I_D = 20A,$ $V_{GS} = 10V$ | - | 33.7 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 8.5 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 7.5 | - | |
| Source-Drain Diode characteristics | | | | | | |
| Diode Forward voltage ⁽³⁾ | V_{DS} | $V_{GS} = 0V, I_S = 1A$ | - | - | 1.2 | V |
| Diode Forward current ⁽⁴⁾ | I_S | | - | - | 20 | A |

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J = 25^\circ C, V_{DD} = 15V, R_G = 25\Omega, L = 0.1mH, I_{AS} = 36A$
3. Pulse Test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board, $t \leq 10$ sec

Test Circuit

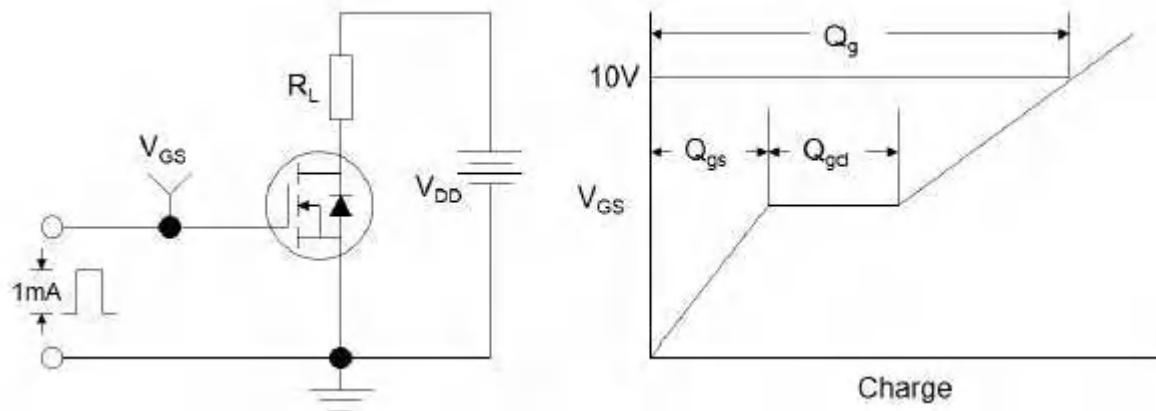


Figure 1: Gate Charge Test Circuit & Waveform

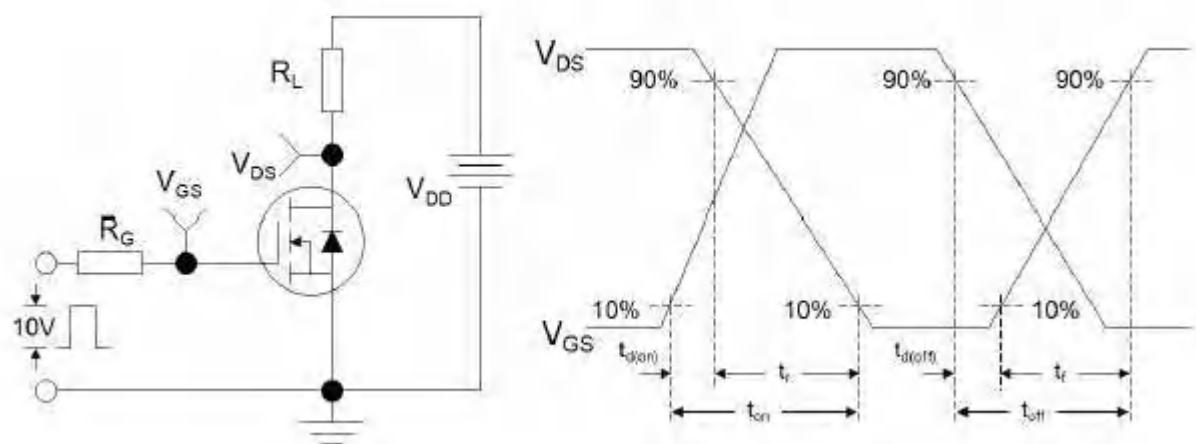


Figure 2: Resistive Switching Test Circuit & Waveforms

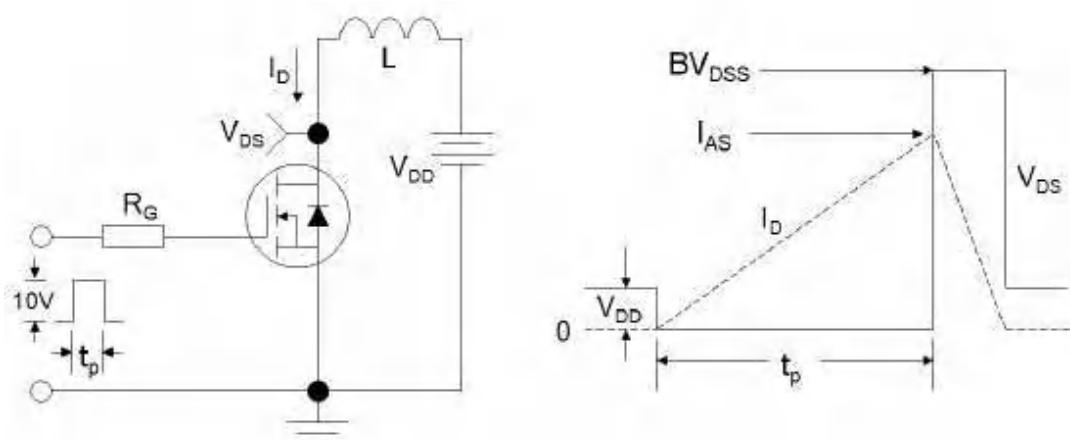


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

Typical Performance Characteristics

Figure 1: Output Characteristics

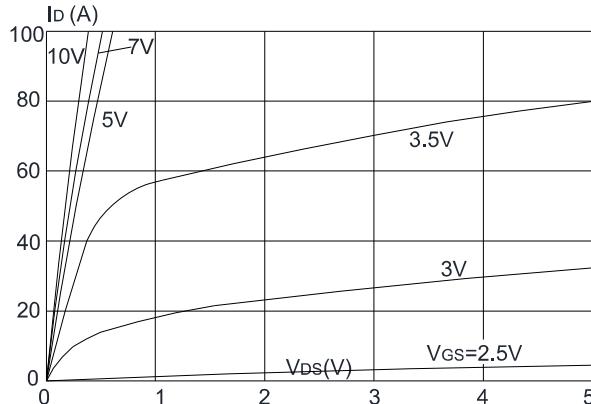


Figure 3: On-resistance vs. Drain Current

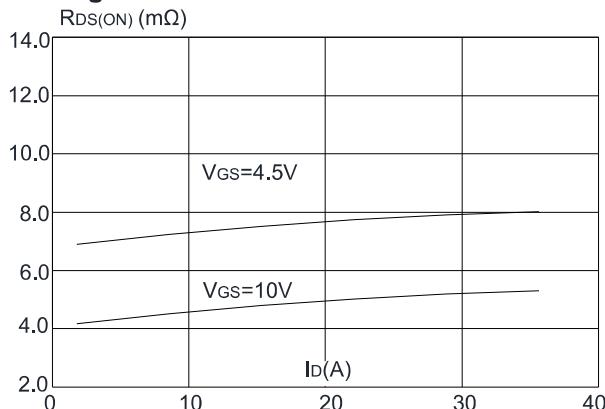


Figure 5: Gate Charge Characteristics

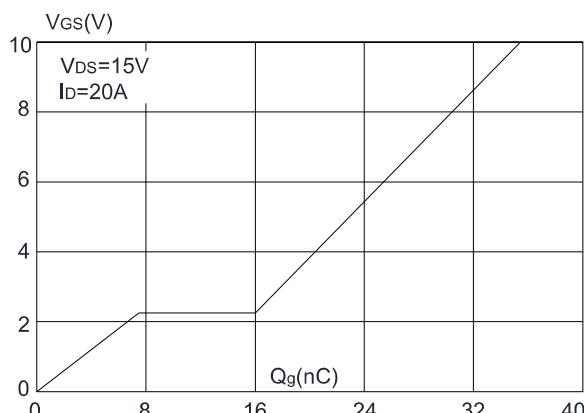


Figure 2: Typical Transfer Characteristics

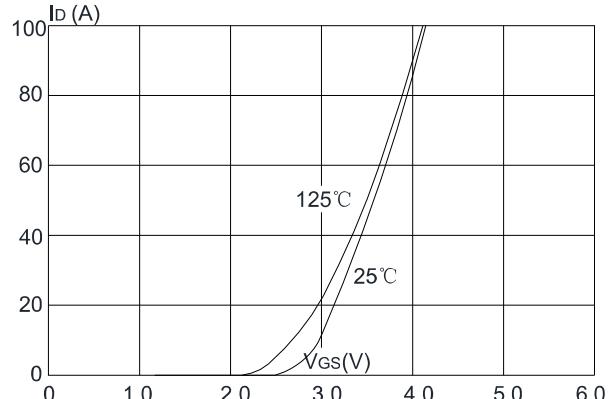


Figure 4: Body Diode Characteristics

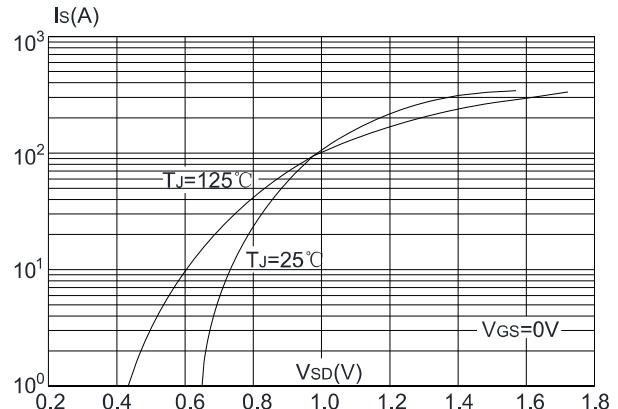


Figure 6: Capacitance Characteristics

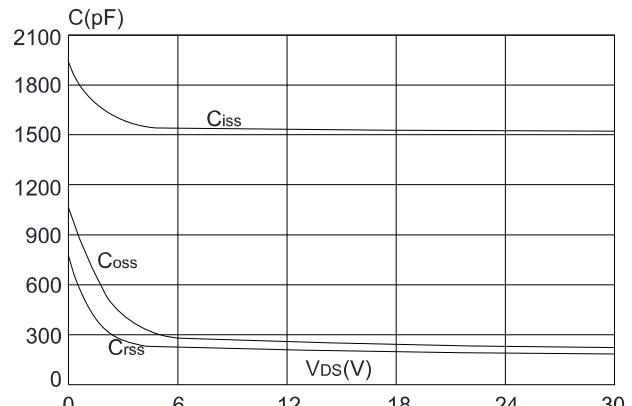


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

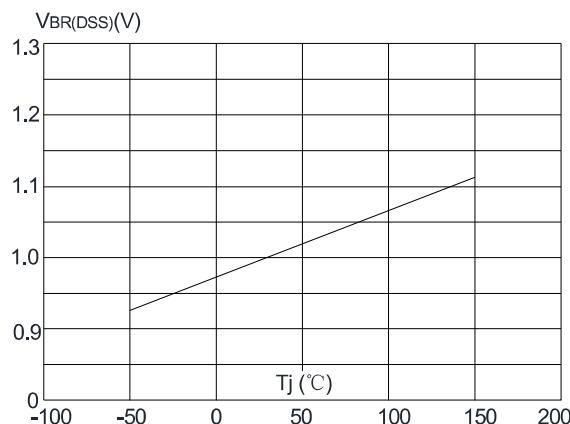


Figure 8: Normalized on Resistance vs. Junction Temperature

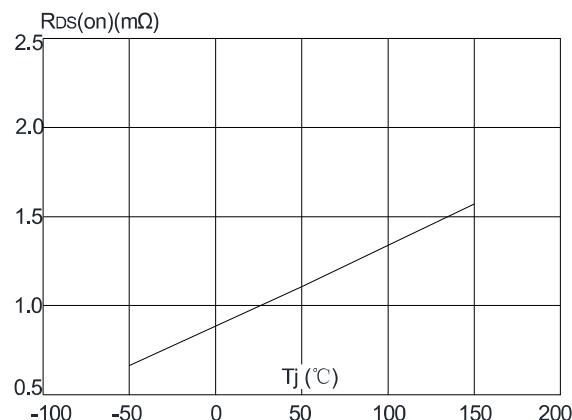


Figure 9: Maximum Safe Operating Area

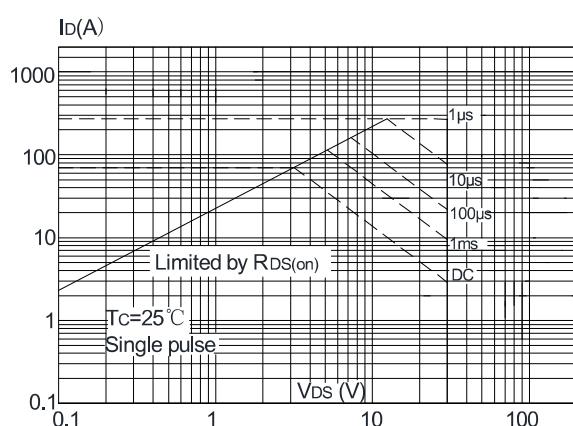


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

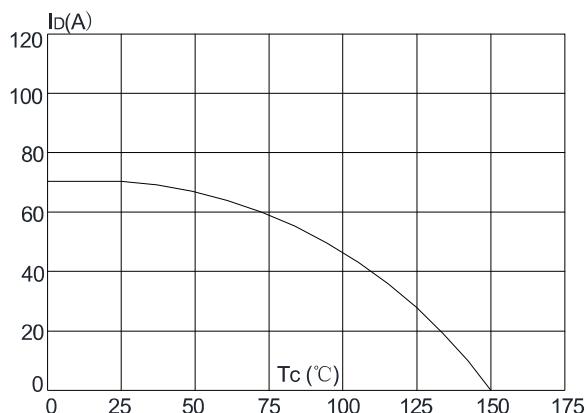
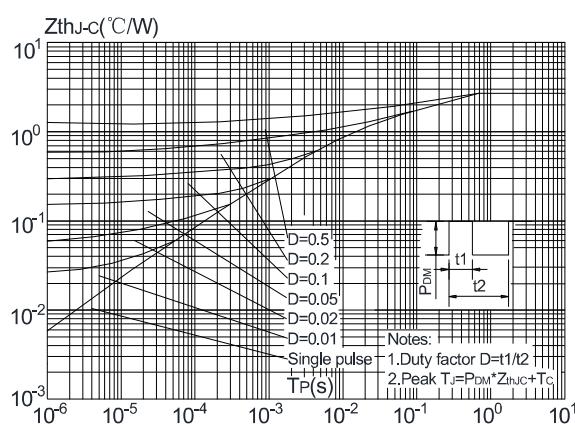
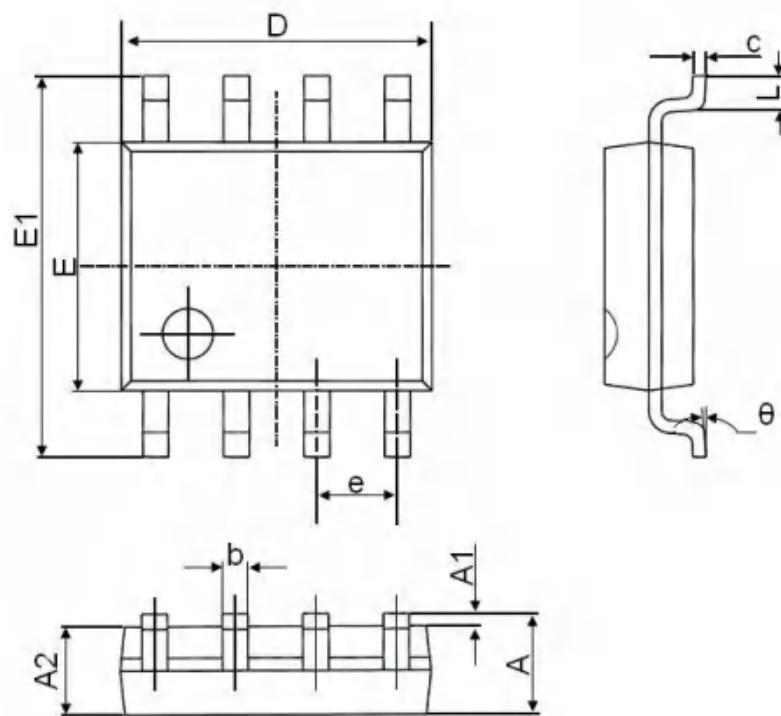


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



SOP-8 Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 1.350 | 1.750 | 0.053 | 0.069 |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 |
| b | 0.330 | 0.510 | 0.013 | 0.020 |
| c | 0.170 | 0.250 | 0.006 | 0.010 |
| D | 4.700 | 5.100 | 0.185 | 0.200 |
| E | 3.800 | 4.000 | 0.150 | 0.157 |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 |
| theta | 0° | 8° | 0° | 8° |